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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I ² C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	48
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 12x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f101lgafa-v0

Table 1-1. List of Ordering Part Numbers

(7/12)

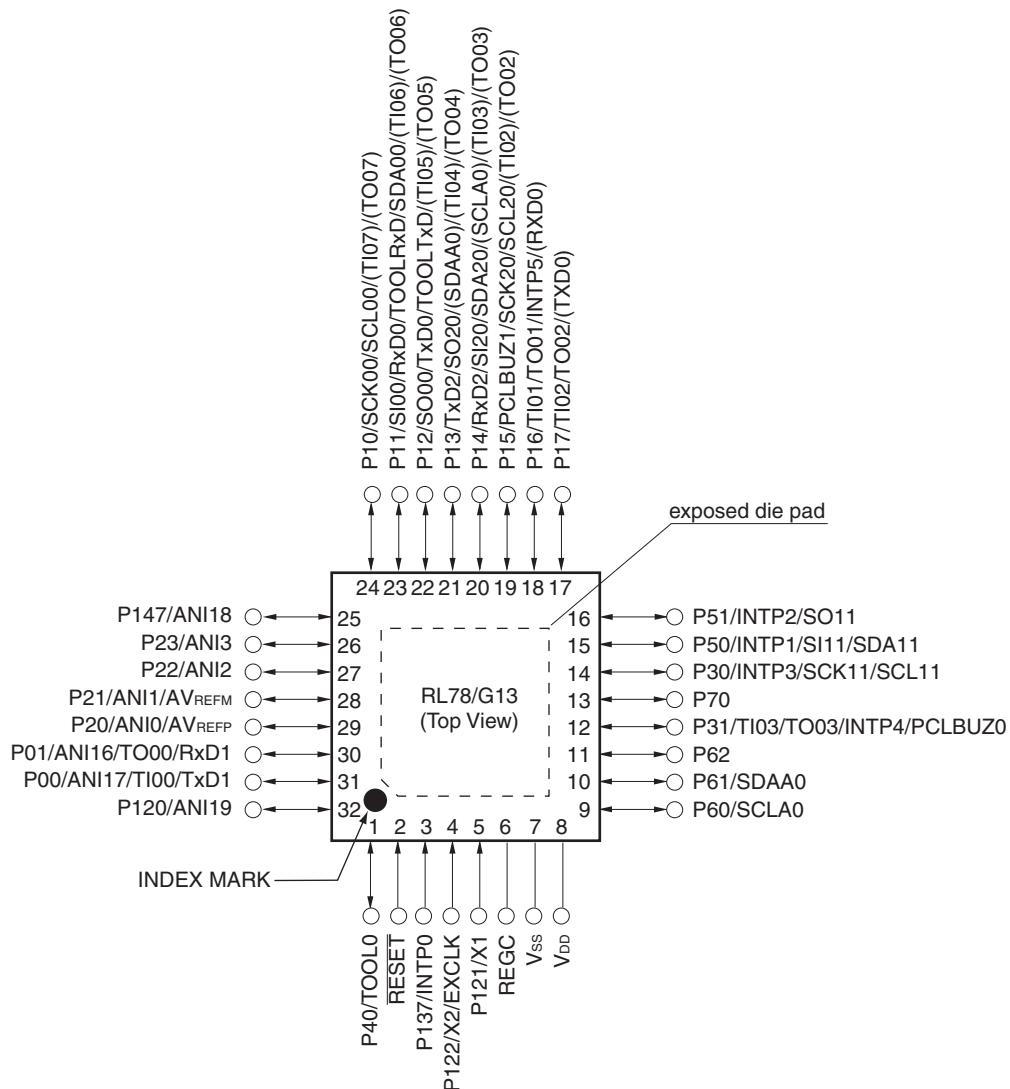
Pin count	Package	Data flash	Fields of Application <small>Note</small>	Ordering Part Number
52 pins	52-pin plastic LQFP (10 × 10 mm, 0.65 mm pitch)	Mounted	A	R5F100JCAFA#V0, R5F100JDAFA#V0, R5F100JEAF#V0, R5F100JFAFA#V0, R5F100JGAFA#V0, R5F100JHAFA#V0, R5F100JJFAFA#V0, R5F100JKAFA#V0, R5F100JLAFA#V0 R5F100JCAFA#X0, R5F100JDAFA#X0, R5F100JEAF#X0, R5F100JFAFA#X0, R5F100JGAFA#X0, R5F100JHAFA#X0, R5F100JJFAFA#X0, R5F100JKAFA#X0, R5F100JLAFA#X0 R5F100JCDSA#V0, R5F100JDDFA#V0, R5F100JEDFA#V0, R5F100JFDFA#V0, R5F100JGDFA#V0, R5F100JHDFA#V0, R5F100JJDFA#V0, R5F100JKDFA#V0, R5F100JLDFA#V0 R5F100JCDSA#X0, R5F100JDDFA#X0, R5F100JEDFA#X0, R5F100JFDFA#X0, R5F100JGDFA#X0, R5F100JHDFA#X0, R5F100JJDFA#X0, R5F100JKDFA#X0, R5F100JLDFA#X0 R5F100JCGFA#V0, R5F100JDGFA#V0, R5F100JEGFA#V0, R5F100JFGFA#V0, R5F100JGGFA#V0, R5F100JHGFA#V0, R5F100JJGFA#V0 R5F100JCGFA#X0, R5F100JDGFA#X0, R5F100JEGFA#X0, R5F100JFGFA#X0, R5F100JGGFA#X0, R5F100JHGFA#X0, R5F100JJGFA#X0
			D	R5F101JCAFA#V0, R5F101JDAFA#V0, R5F101JEAF#V0, R5F101JFAFA#V0, R5F101JGAFA#V0, R5F101JHAFA#V0, R5F101JJFAFA#V0, R5F101JKAFA#V0, R5F101JLAFA#V0 R5F101JCAFA#X0, R5F101JDAFA#X0, R5F101JEAF#X0, R5F101JFAFA#X0, R5F101JGAFA#X0, R5F101JHAFA#X0, R5F101JJFAFA#X0, R5F101JKAFA#X0, R5F101JLAFA#X0 R5F101JCDSA#V0, R5F101JDDFA#V0, R5F101JEDFA#V0, R5F101JFDFA#V0, R5F101JGDFA#V0, R5F101JHDFA#V0, R5F101JJDFA#V0, R5F101JKDFA#V0, R5F101JLDFA#V0 R5F101JCDSA#X0, R5F101JDDFA#X0, R5F101JEDFA#X0, R5F101JFDFA#X0, R5F101JGDFA#X0, R5F101JHDFA#X0, R5F101JJDFA#X0, R5F101JKDFA#X0, R5F101JLDFA#X0

Note For the fields of application, refer to **Figure 1-1 Part Number, Memory Size, and Package of RL78/G13**.

Caution The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

1.3.5 32-pin products

- 32-pin plastic HWQFN (5 × 5 mm, 0.5 mm pitch)



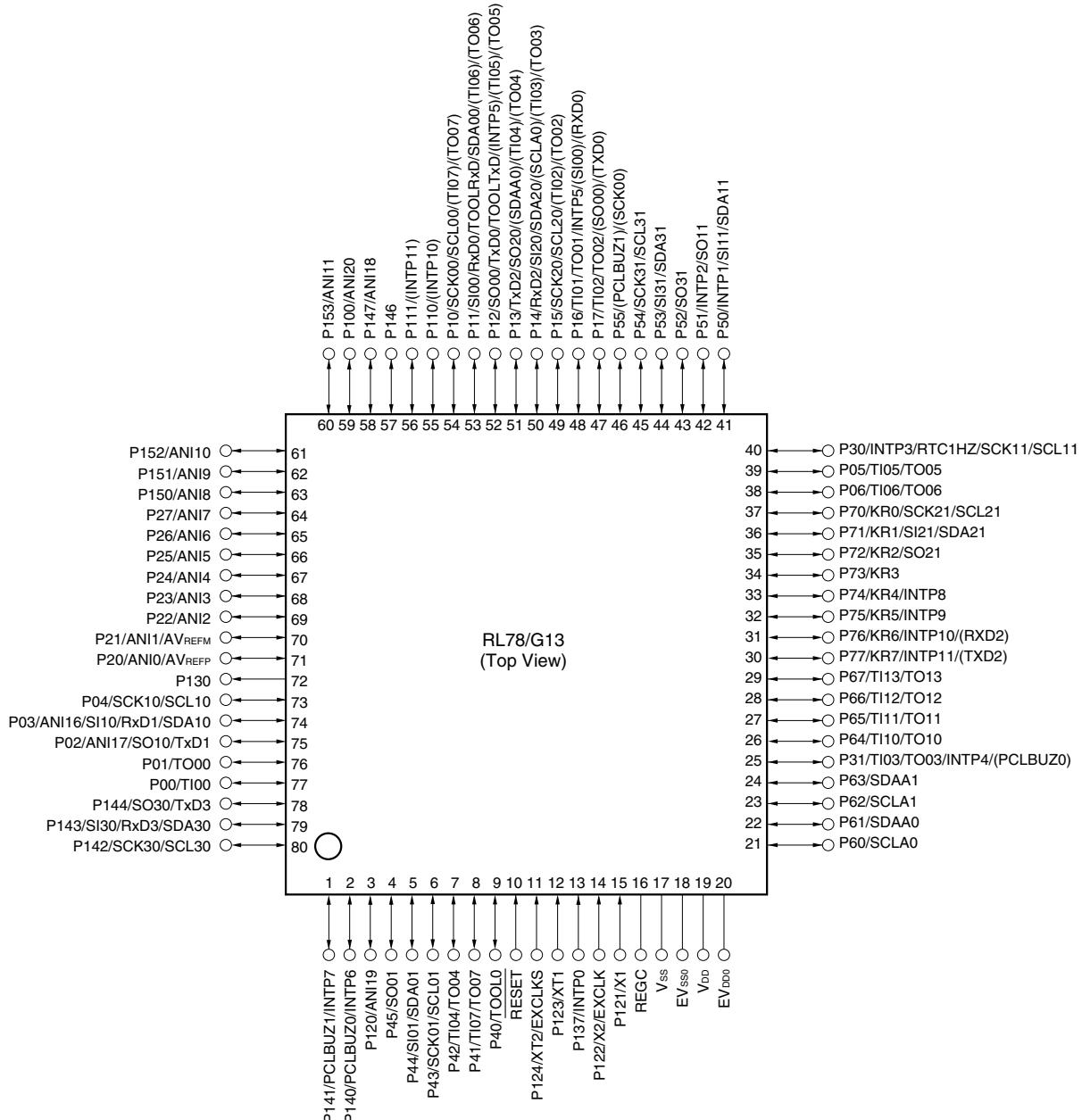
Caution Connect the REGC pin to V_{ss} via a capacitor (0.47 to 1 μ F).

Remarks 1. For pin identification, see **1.4 Pin Identification**.

2. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.
3. It is recommended to connect an exposed die pad to V_{ss}.

1.3.12 80-pin products

- 80-pin plastic LQFP (14 × 14 mm, 0.65 mm pitch)
- 80-pin plastic LFQFP (12 × 12 mm, 0.5 mm pitch)



Cautions

1. Make EV_{VSS0} pin the same potential as V_{SS} pin.

2. Make V_{DD} pin the potential that is higher than EV_{VDD0} pin.

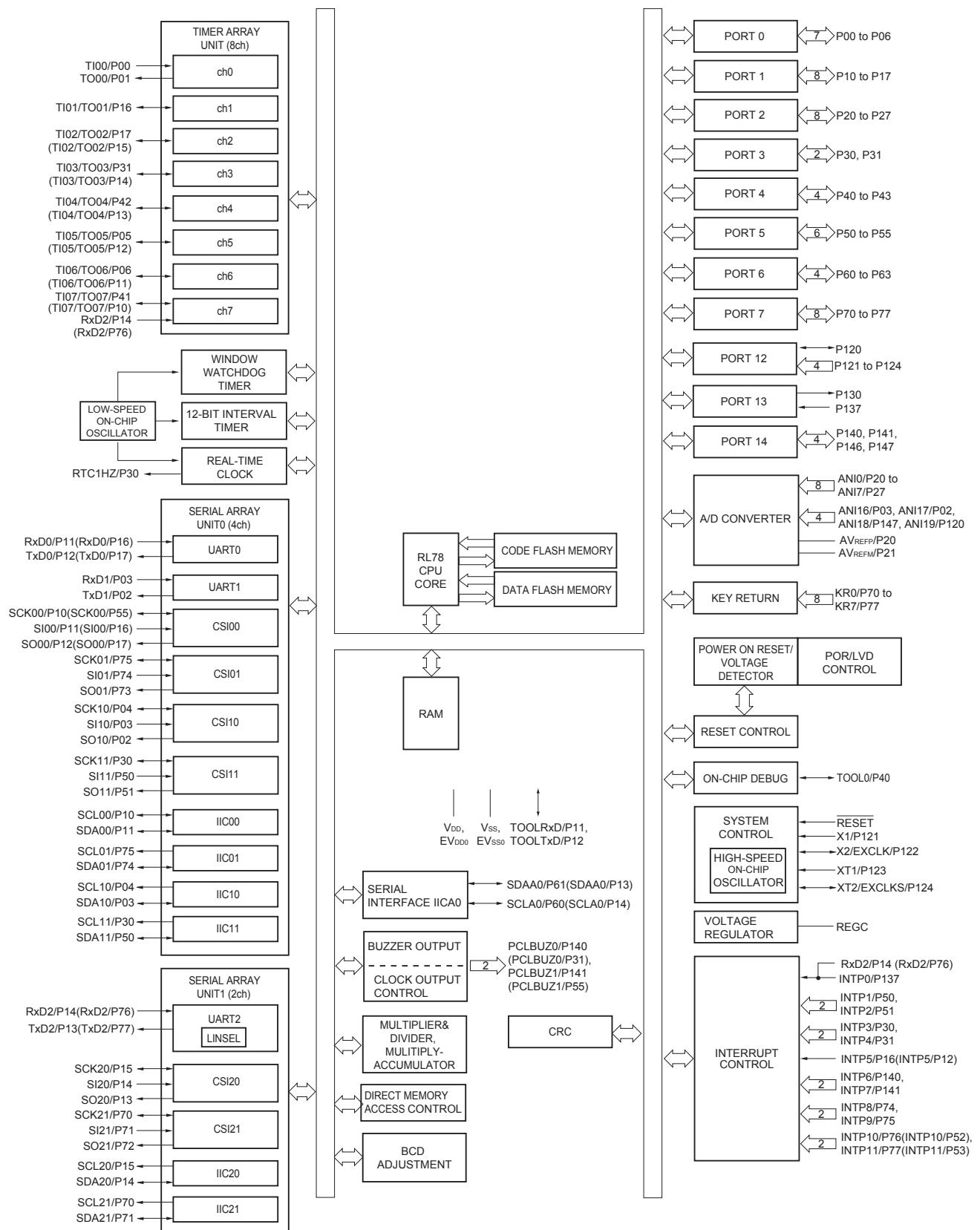
3. Connect the REGC pin to V_{SS} via a capacitor (0.47 to 1 μ F).

Remarks

1. For pin identification, see **1.4 Pin Identification**.

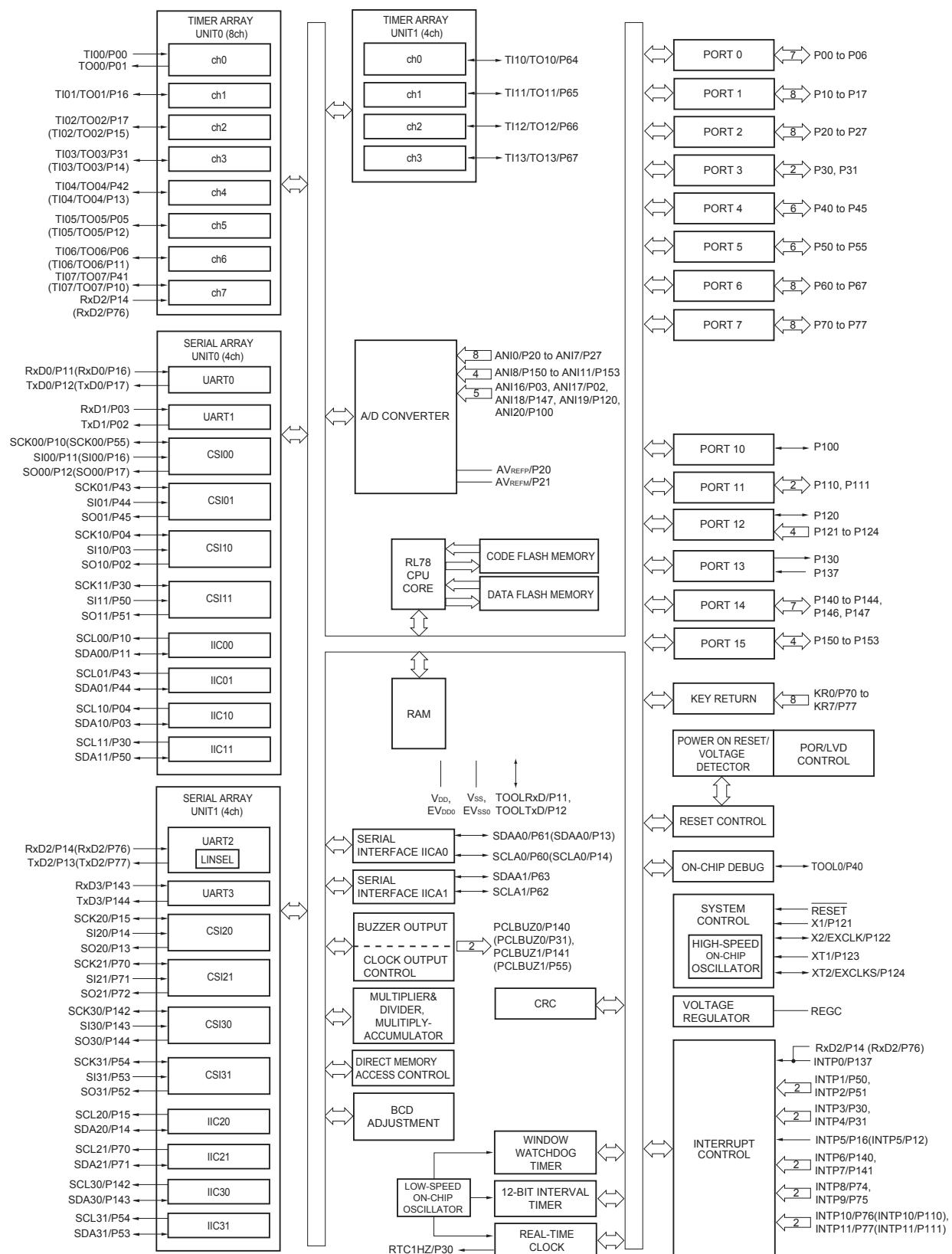
2. When using the microcontroller for an application where the noise generated inside the microcontroller must be reduced, it is recommended to supply separate powers to the V_{DD} and EV_{VDD0} pins and connect the V_{SS} and EV_{VSS0} pins to separate ground lines.
3. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

1.5.11 64-pin products



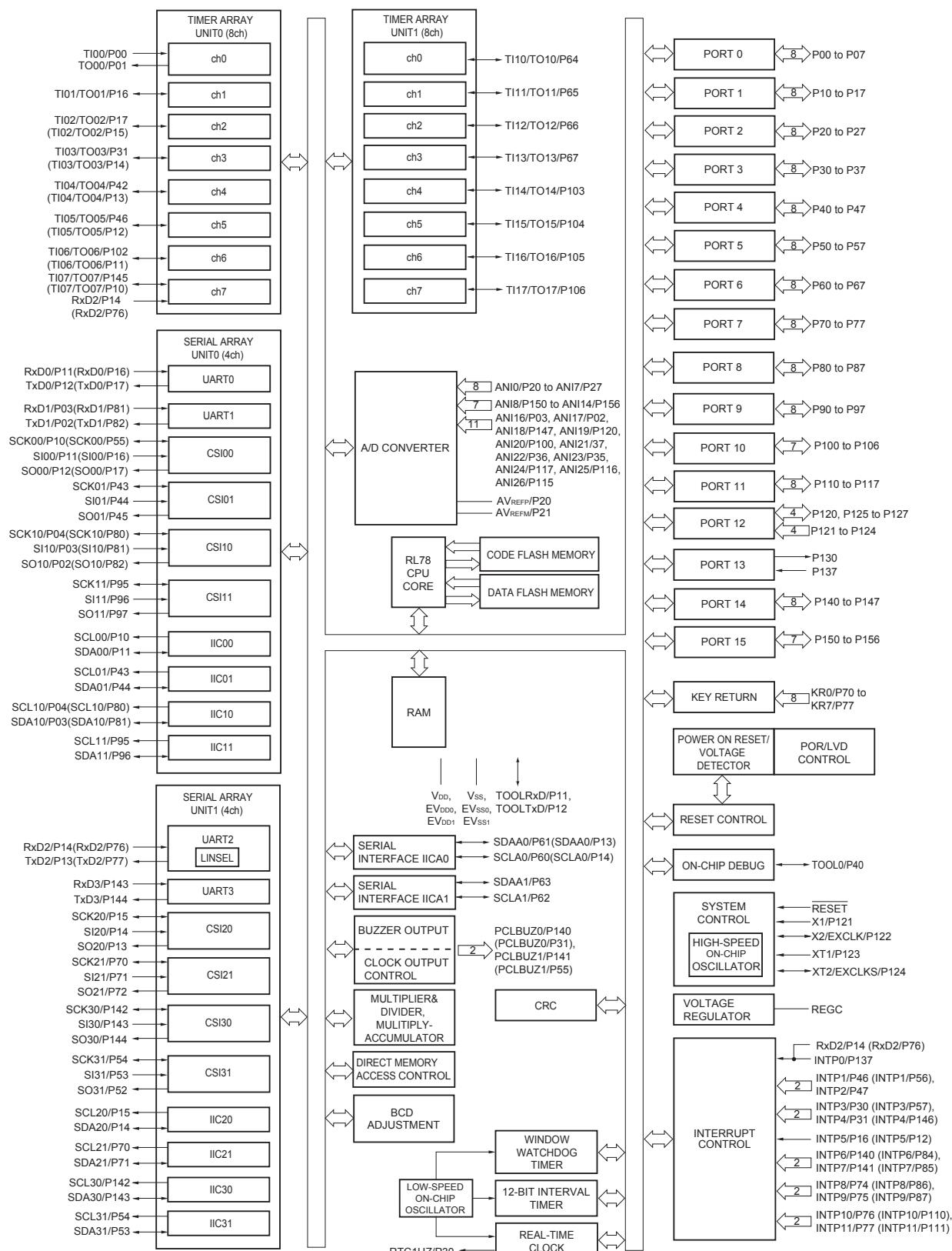
Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

1.5.12 80-pin products



Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

1.5.14 128-pin products

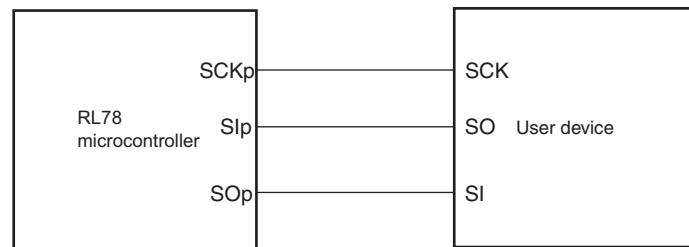


Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

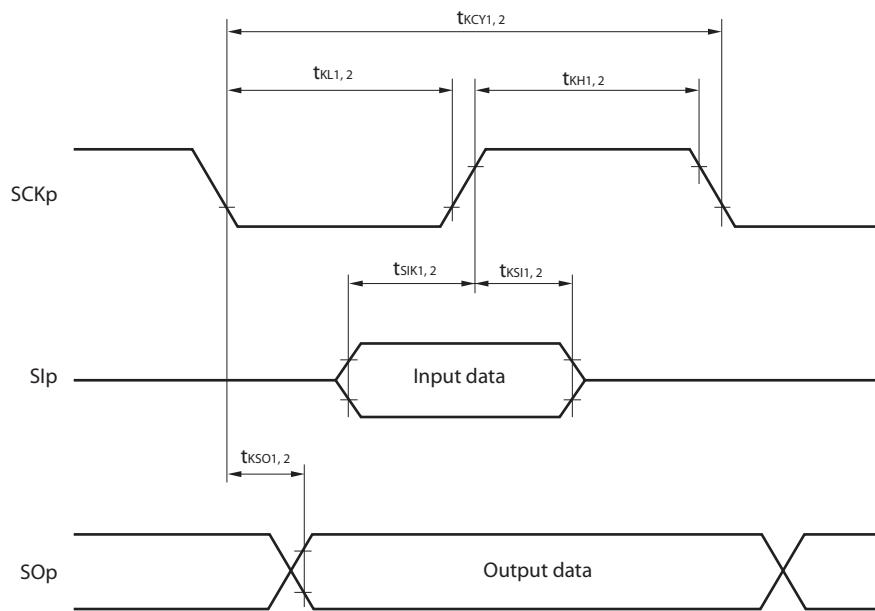
6. Current flowing only to the A/D converter. The supply current of the RL78 microcontrollers is the sum of I_{DD1} or I_{DD2} and I_{ADC} when the A/D converter operates in an operation mode or the HALT mode.
7. Current flowing only to the LVD circuit. The supply current of the RL78 microcontrollers is the sum of I_{DD1} , I_{DD2} or I_{DD3} and I_{LVD} when the LVD circuit is in operation.
8. Current flowing only during data flash rewrite.
9. Current flowing only during self programming.
10. For shift time to the SNOOZE mode, see **18.3.3 SNOOZE mode**.

Remarks

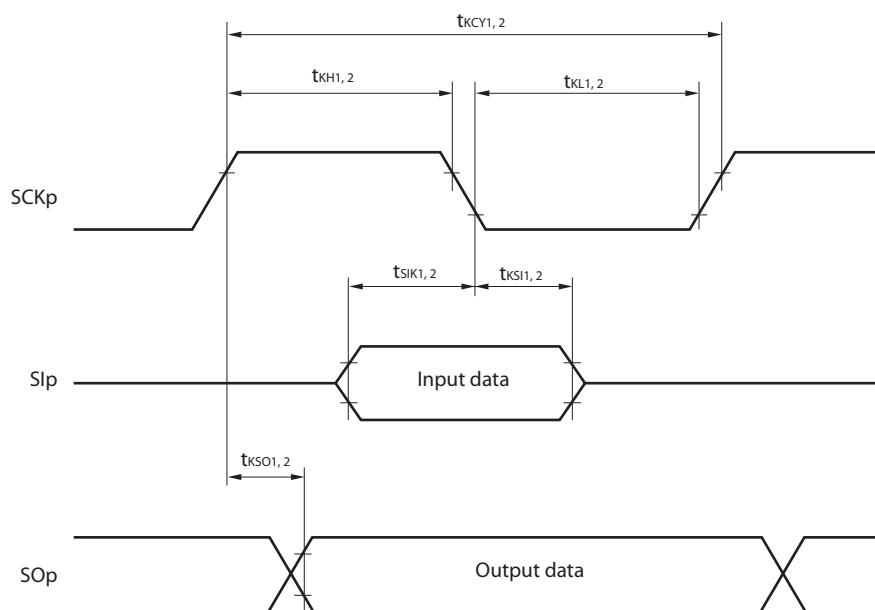
- 1. f_{IL} : Low-speed on-chip oscillator clock frequency
- 2. f_{SUB} : Subsystem clock frequency (XT1 clock oscillation frequency)
- 3. f_{CLK} : CPU/peripheral hardware clock frequency
- 4. Temperature condition of the TYP. value is $T_A = 25^\circ\text{C}$

CSI mode connection diagram (during communication at same potential)

CSI mode serial transfer timing (during communication at same potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



CSI mode serial transfer timing (during communication at same potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



- Remarks**
1. p: CSI number ($p = 00, 01, 10, 11, 20, 21, 30, 31$)
 2. m: Unit number, n: Channel number ($mn = 00$ to $03, 10$ to 13)

(5) During communication at same potential (simplified I²C mode) (2/2)(TA = -40 to +85°C, 1.6 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{SS0} = EV_{SS1} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Data setup time (reception)	t _{SU:DAT}	2.7 V ≤ EV _{DD0} ≤ 5.5 V, C _b = 50 pF, R _b = 2.7 kΩ	1/f _{MCK} + 85 Note2		1/f _{MCK} + 145 Note2		1/f _{MCK} + 145 Note2		ns
		1.8 V ≤ EV _{DD0} ≤ 5.5 V, C _b = 100 pF, R _b = 3 kΩ	1/f _{MCK} + 145 Note2		1/f _{MCK} + 145 Note2		1/f _{MCK} + 145 Note2		ns
		1.8 V ≤ EV _{DD0} < 2.7 V, C _b = 100 pF, R _b = 5 kΩ	1/f _{MCK} + 230 Note2		1/f _{MCK} + 230 Note2		1/f _{MCK} + 230 Note2		ns
		1.7 V ≤ EV _{DD0} < 1.8 V, C _b = 100 pF, R _b = 5 kΩ	1/f _{MCK} + 290 Note2		1/f _{MCK} + 290 Note2		1/f _{MCK} + 290 Note2		ns
		1.6 V ≤ EV _{DD0} < 1.8 V, C _b = 100 pF, R _b = 5 kΩ	—		1/f _{MCK} + 290 Note2		1/f _{MCK} + 290 Note2		ns
Data hold time (transmission)	t _{HD:DAT}	2.7 V ≤ EV _{DD0} ≤ 5.5 V, C _b = 50 pF, R _b = 2.7 kΩ	0	305	0	305	0	305	ns
		1.8 V ≤ EV _{DD0} ≤ 5.5 V, C _b = 100 pF, R _b = 3 kΩ	0	355	0	355	0	355	ns
		1.8 V ≤ EV _{DD0} < 2.7 V, C _b = 100 pF, R _b = 5 kΩ	0	405	0	405	0	405	ns
		1.7 V ≤ EV _{DD0} < 1.8 V, C _b = 100 pF, R _b = 5 kΩ	0	405	0	405	0	405	ns
		1.6 V ≤ EV _{DD0} < 1.8 V, C _b = 100 pF, R _b = 5 kΩ	—		0	405	0	405	ns

Notes 1. The value must also be equal to or less than f_{MCK}/4.2. Set the f_{MCK} value to keep the hold time of SCL_r = "L" and SCL_r = "H".**Caution** Select the normal input buffer and the N-ch open drain output (V_{DD} tolerance (When 20- to 52-pin products)/EV_{DD} tolerance (When 64- to 128-pin products)) mode for the SDAr pin and the normal output mode for the SCL_r pin by using port input mode register g (PIMg) and port output mode register h (POMh).

(Remarks are listed on the next page.)

**(8) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output)
(1/3)**

($T_A = -40$ to $+85^\circ\text{C}$, $1.8 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time	t _{KCY1}	t _{KCY1} ≥ 4/f _{CLK}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	300		1150		1150		ns
			2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	500		1150		1150		ns
			1.8 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V ^{Note} , C _b = 30 pF, R _b = 5.5 kΩ	1150		1150		1150		ns
SCKp high-level width	t _{Kh1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	t _{KCY1} /2 – 75		t _{KCY1} /2 – 75		t _{KCY1} /2 – 75			ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	t _{KCY1} /2 – 170		t _{KCY1} /2 – 170		t _{KCY1} /2 – 170			ns
		1.8 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V ^{Note} , C _b = 30 pF, R _b = 5.5 kΩ	t _{KCY1} /2 – 458		t _{KCY1} /2 – 458		t _{KCY1} /2 – 458			ns
SCKp low-level width	t _{KL1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	t _{KCY1} /2 – 12		t _{KCY1} /2 – 50		t _{KCY1} /2 – 50			ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	t _{KCY1} /2 – 18		t _{KCY1} /2 – 50		t _{KCY1} /2 – 50			ns
		1.8 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V ^{Note} , C _b = 30 pF, R _b = 5.5 kΩ	t _{KCY1} /2 – 50		t _{KCY1} /2 – 50		t _{KCY1} /2 – 50			ns

Note Use it with $EV_{DD0} \geq V_b$.

Caution Select the TTL input buffer for the S_{Op} pin and the N-ch open drain output (V_{DD} tolerance (When 20- to 52-pin products)/EV_{DD} tolerance (When 64- to 128-pin products)) mode for the S_{Op} pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

(Remarks are listed two pages after the next page.)

(9) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (slave mode, SCKp... external clock input)

($T_A = -40$ to $+85^\circ\text{C}$, $1.8 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$) (2/2)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp high-/low-level width	t_{KH2} , t_{KL2}	4.0 V $\leq EV_{DD0} \leq 5.5$ V, 2.7 V $\leq V_b \leq 4.0$ V	$t_{KCY2}/2$ – 12		$t_{KCY2}/2$ – 50		$t_{KCY2}/2$ – 50		ns
		2.7 V $\leq EV_{DD0} < 4.0$ V, 2.3 V $\leq V_b \leq 2.7$ V	$t_{KCY2}/2$ – 18		$t_{KCY2}/2$ – 50		$t_{KCY2}/2$ – 50		ns
		1.8 V $\leq EV_{DD0} < 3.3$ V, 1.6 V $\leq V_b \leq 2.0$ V ^{Note 2}	$t_{KCY2}/2$ – 50		$t_{KCY2}/2$ – 50		$t_{KCY2}/2$ – 50		ns
Slp setup time (to SCKp↑) ^{Note 3}	t_{SIK2}	4.0 V $\leq EV_{DD0} \leq 5.5$ V, 2.7 V $\leq V_b \leq 4.0$ V	$1/f_{MCK}$ + 20		$1/f_{MCK}$ + 30		$1/f_{MCK}$ + 30		ns
		2.7 V $\leq EV_{DD0} < 4.0$ V, 2.3 V $\leq V_b \leq 2.7$ V	$1/f_{MCK}$ + 20		$1/f_{MCK}$ + 30		$1/f_{MCK}$ + 30		ns
		1.8 V $\leq EV_{DD0} < 3.3$ V, 1.6 V $\leq V_b \leq 2.0$ V ^{Note 2}	$1/f_{MCK}$ + 30		$1/f_{MCK}$ + 30		$1/f_{MCK}$ + 30		ns
Slp hold time (from SCKp↑) ^{Note 4}	t_{SIS2}		$1/f_{MCK} +$ 31		$1/f_{MCK}$ + 31		$1/f_{MCK}$ + 31		ns
Delay time from SCKp↓ to SOp output ^{Note 5}	t_{KS02}	4.0 V $\leq EV_{DD0} \leq 5.5$ V, 2.7 V $\leq V_b \leq 4.0$ V, $C_b = 30 \text{ pF}$, $R_b = 1.4 \text{ k}\Omega$		$2/f_{MCK}$ + 120		$2/f_{MCK}$ + 573		$2/f_{MCK}$ + 573	ns
		2.7 V $\leq EV_{DD0} < 4.0$ V, 2.3 V $\leq V_b \leq 2.7$ V, $C_b = 30 \text{ pF}$, $R_b = 2.7 \text{ k}\Omega$		$2/f_{MCK}$ + 214		$2/f_{MCK}$ + 573		$2/f_{MCK}$ + 573	ns
		1.8 V $\leq EV_{DD0} < 3.3$ V, 1.6 V $\leq V_b \leq 2.0$ V ^{Note 2} , $C_b = 30 \text{ pF}$, $R_b = 5.5 \text{ k}\Omega$		$2/f_{MCK}$ + 573		$2/f_{MCK}$ + 573		$2/f_{MCK}$ + 573	ns

Notes 1. Transfer rate in the SNOOZE mode : MAX. 1 Mbps

2. Use it with $EV_{DD0} \geq V_b$.
3. When $DAP_{mn} = 0$ and $CKP_{mn} = 0$, or $DAP_{mn} = 1$ and $CKP_{mn} = 1$. The Slp setup time becomes “to SCKp↑” when $DAP_{mn} = 0$ and $CKP_{mn} = 1$, or $DAP_{mn} = 1$ and $CKP_{mn} = 0$.
4. When $DAP_{mn} = 0$ and $CKP_{mn} = 0$, or $DAP_{mn} = 1$ and $CKP_{mn} = 1$. The Slp hold time becomes “from SCKp↑” when $DAP_{mn} = 0$ and $CKP_{mn} = 1$, or $DAP_{mn} = 1$ and $CKP_{mn} = 0$.
5. When $DAP_{mn} = 0$ and $CKP_{mn} = 0$, or $DAP_{mn} = 1$ and $CKP_{mn} = 1$. The delay time to SOp output becomes “from SCKp↑” when $DAP_{mn} = 0$ and $CKP_{mn} = 1$, or $DAP_{mn} = 1$ and $CKP_{mn} = 0$.

Caution Select the TTL input buffer for the Slp pin and the N-ch open drain output (V_{DD} tolerance (for the 20- to 52-pin products)/ EV_{DD} tolerance (for the 64- to 128-pin products)) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL} , see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the next page.)

(2) Flash ROM: 96 to 256 KB of 30- to 100-pin products

 $(T_A = -40$ to $+105^\circ\text{C}$, $2.4 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$) (1/2)

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD1}	Operating mode	HS (high-speed main) mode Note 5	$f_{IH} = 32 \text{ MHz}$ ^{Note 3}	Basic operation	$V_{DD} = 5.0 \text{ V}$		2.3		mA
					Normal operation	$V_{DD} = 3.0 \text{ V}$		2.3		mA
					Normal operation	$V_{DD} = 5.0 \text{ V}$		5.2	9.2	mA
					Normal operation	$V_{DD} = 3.0 \text{ V}$		5.2	9.2	mA
				$f_{IH} = 24 \text{ MHz}$ ^{Note 3}	Normal operation	$V_{DD} = 5.0 \text{ V}$		4.1	7.0	mA
					Normal operation	$V_{DD} = 3.0 \text{ V}$		4.1	7.0	mA
		HS (high-speed main) mode Note 5	$f_{MX} = 20 \text{ MHz}$ ^{Note 2} , $V_{DD} = 5.0 \text{ V}$	Normal operation	Square wave input		3.4	5.9		mA
				Normal operation	Resonator connection		3.6	6.0		mA
				Normal operation	Square wave input		3.4	5.9		mA
				Normal operation	Resonator connection		3.6	6.0		mA
			$f_{MX} = 10 \text{ MHz}$ ^{Note 2} , $V_{DD} = 5.0 \text{ V}$	Normal operation	Square wave input		2.1	3.5		mA
				Normal operation	Resonator connection		2.1	3.5		mA
			$f_{MX} = 10 \text{ MHz}$ ^{Note 2} , $V_{DD} = 3.0 \text{ V}$	Normal operation	Square wave input		2.1	3.5		mA
				Normal operation	Resonator connection		2.1	3.5		mA
		Subsystem clock operation	$f_{SUB} = 32.768 \text{ kHz}$ ^{Note 4} $T_A = -40^\circ\text{C}$	Normal operation	Square wave input		4.8	5.9		μA
				Normal operation	Resonator connection		4.9	6.0		μA
				Normal operation	Square wave input		4.9	5.9		μA
				Normal operation	Resonator connection		5.0	6.0		μA
			$f_{SUB} = 32.768 \text{ kHz}$ ^{Note 4} $T_A = +25^\circ\text{C}$	Normal operation	Square wave input		5.0	7.6		μA
				Normal operation	Resonator connection		5.1	7.7		μA
			$f_{SUB} = 32.768 \text{ kHz}$ ^{Note 4} $T_A = +50^\circ\text{C}$	Normal operation	Square wave input		5.2	9.3		μA
				Normal operation	Resonator connection		5.3	9.4		μA
			$f_{SUB} = 32.768 \text{ kHz}$ ^{Note 4} $T_A = +70^\circ\text{C}$	Normal operation	Square wave input		5.7	13.3		μA
				Normal operation	Resonator connection		5.8	13.4		μA
			$f_{SUB} = 32.768 \text{ kHz}$ ^{Note 4} $T_A = +85^\circ\text{C}$	Normal operation	Square wave input		10.0	46.0		μA
				Normal operation	Resonator connection		10.0	46.0		μA

(Notes and Remarks are listed on the next page.)

(2) During communication at same potential (CSI mode) (master mode, SCKp... internal clock output)

(TA = -40 to +105°C, 2.4 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{SS0} = EV_{SS1} = 0 V)

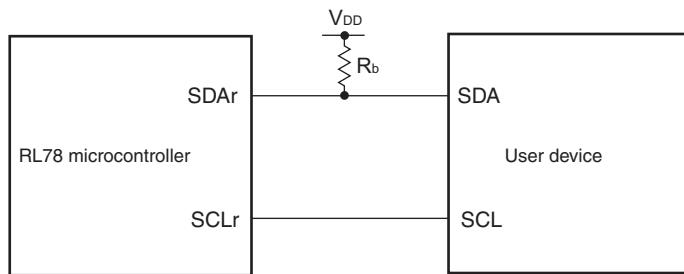
Parameter	Symbol	Conditions		HS (high-speed main) Mode		Unit
				MIN.	MAX.	
SCKp cycle time	t _{KCY1}	t _{KCY1} ≥ 4/f _{CLK}	2.7 V ≤ EV _{DD0} ≤ 5.5 V	250		ns
			2.4 V ≤ EV _{DD0} ≤ 5.5 V	500		ns
SCKp high-/low-level width	t _{KH1} , t _{KL1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V		t _{KCY1} /2 – 24		ns
		2.7 V ≤ EV _{DD0} ≤ 5.5 V		t _{KCY1} /2 – 36		ns
		2.4 V ≤ EV _{DD0} ≤ 5.5 V		t _{KCY1} /2 – 76		ns
Slp setup time (to SCKp↑) ^{Note 1}	t _{SIK1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V		66		ns
		2.7 V ≤ EV _{DD0} ≤ 5.5 V		66		ns
		2.4 V ≤ EV _{DD0} ≤ 5.5 V		113		ns
Slp hold time (from SCKp↑) ^{Note 2}	t _{SKI1}			38		ns
Delay time from SCKp↓ to SOp output ^{Note 3}	t _{KSO1}	C = 30 pF ^{Note 4}			50	ns

- Notes**
- When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp setup time becomes “to SCKp↓” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
 - When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp hold time becomes “from SCKp↓” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
 - When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes “from SCKp↑” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
 - C is the load capacitance of the SCKp and SOp output lines.

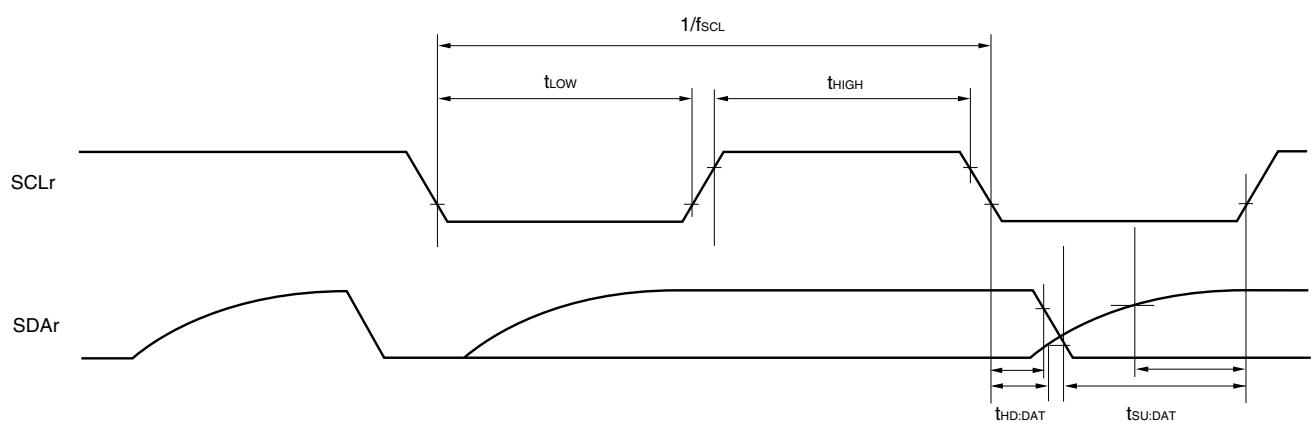
Caution Select the normal input buffer for the Slp pin and the normal output mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

- Remarks**
- p: CSI number (p = 00, 01, 10, 11, 20, 21, 30, 31), m: Unit number (m = 0, 1), n: Channel number (n = 0 to 3),
g: PIM and POM numbers (g = 0, 1, 4, 5, 8, 14)
 - f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

Simplified I²C mode connection diagram (during communication at same potential)



Simplified I²C mode serial transfer timing (during communication at same potential)



Remarks 1. $R_b[\Omega]$:Communication line (SDAr) pull-up resistance, $C_b[F]$: Communication line (SDAr, SCLr) load capacitance

2. r: IIC number ($r = 00, 01, 10, 11, 20, 21, 30, 31$), g: PIM number ($g = 0, 1, 4, 5, 8, 14$), h: POM number ($g = 0, 1, 4, 5, 7 \text{ to } 9, 14$)

3. f_{MCK} : Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number ($m = 0, 1$), n: Channel number ($n = 0 \text{ to } 3$), mn = 00 to 03, 10 to 13)

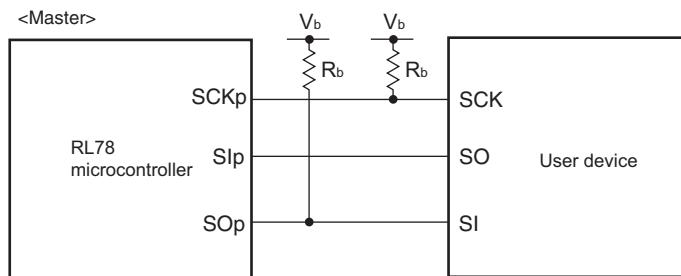
(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output) (1/3)

(TA = -40 to +105°C, 2.4 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{ss} = EV_{SS0} = EV_{SS1} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
SCKp cycle time	t _{KCY1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	600		ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	1000		ns
		2.4 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V, C _b = 30 pF, R _b = 5.5 kΩ	2300		ns
SCKp high-level width	t _{KH1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	t _{KCY1} /2 – 150		ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	t _{KCY1} /2 – 340		ns
		2.4 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V, C _b = 30 pF, R _b = 5.5 kΩ	t _{KCY1} /2 – 916		ns
SCKp low-level width	t _{KL1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	t _{KCY1} /2 – 24		ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	t _{KCY1} /2 – 36		ns
		2.4 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V, C _b = 30 pF, R _b = 5.5 kΩ	t _{KCY1} /2 – 100		ns

Caution Select the TTL input buffer for the S_lp pin and the N-ch open drain output (V_{DD} tolerance (for the 20- to 52-pin products)/EV_{DD} tolerance (for the 64- to 100-pin products)) mode for the SO_p pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

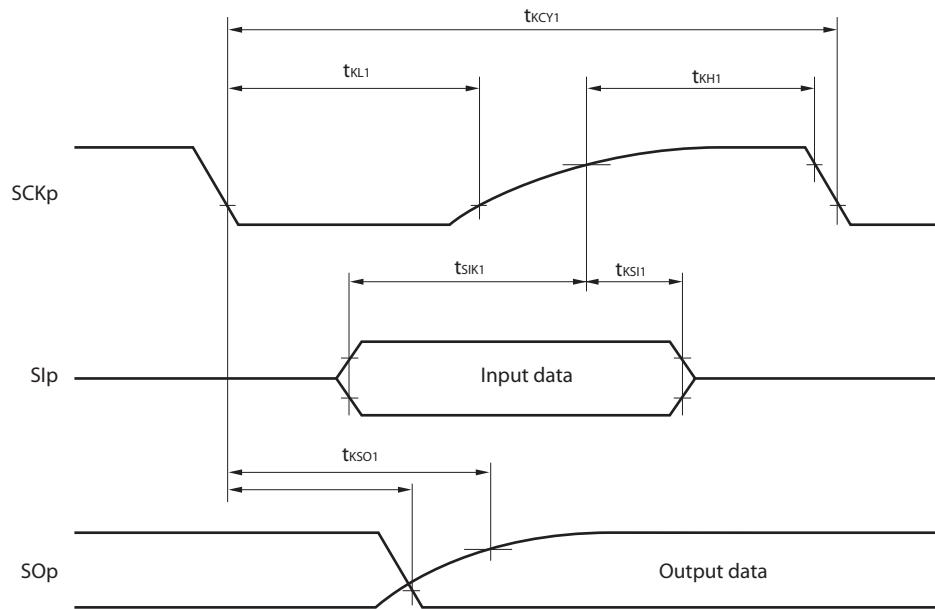
(Remarks are listed two pages after the next page.)

CSI mode connection diagram (during communication at different potential)

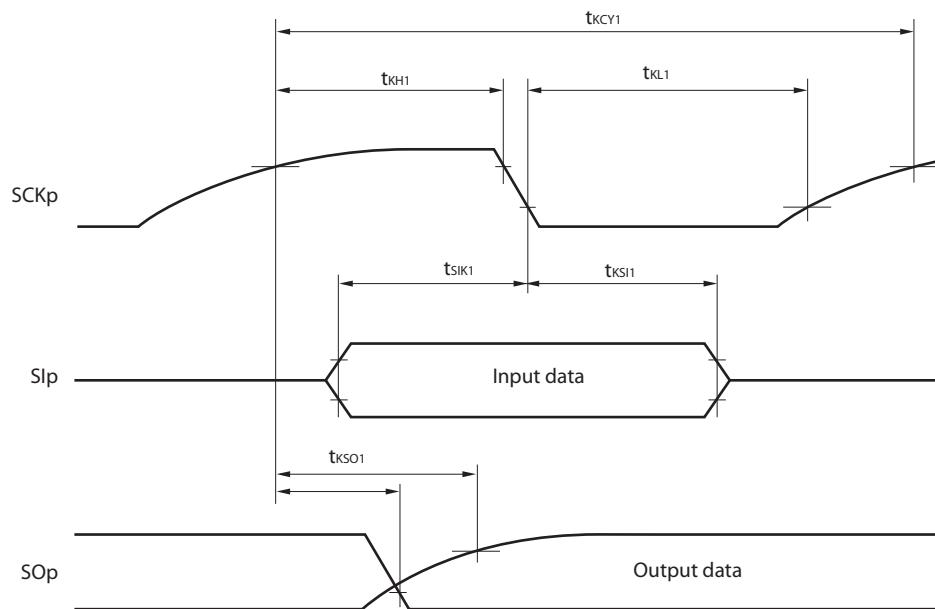
- Remarks**
1. $R_b[\Omega]$: Communication line (SCKp, SOp) pull-up resistance, $C_b[F]$: Communication line (SCKp, SOp) load capacitance, $V_b[V]$: Communication line voltage
 2. p: CSI number ($p = 00, 01, 10, 20, 30, 31$), m: Unit number , n: Channel number ($mn = 00, 01, 02, 10, 12, 13$), g: PIM and POM number ($g = 0, 1, 4, 5, 8, 14$)
 3. fmck: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn).
m: Unit number, n: Channel number ($mn = 00$))
 4. CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential.
Use other CSI for communication at different potential.

CSI mode serial transfer timing (master mode) (during communication at different potential)

(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)

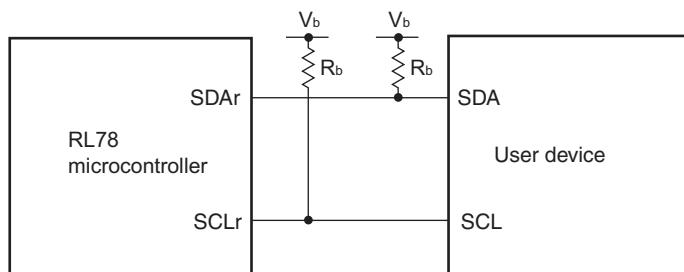
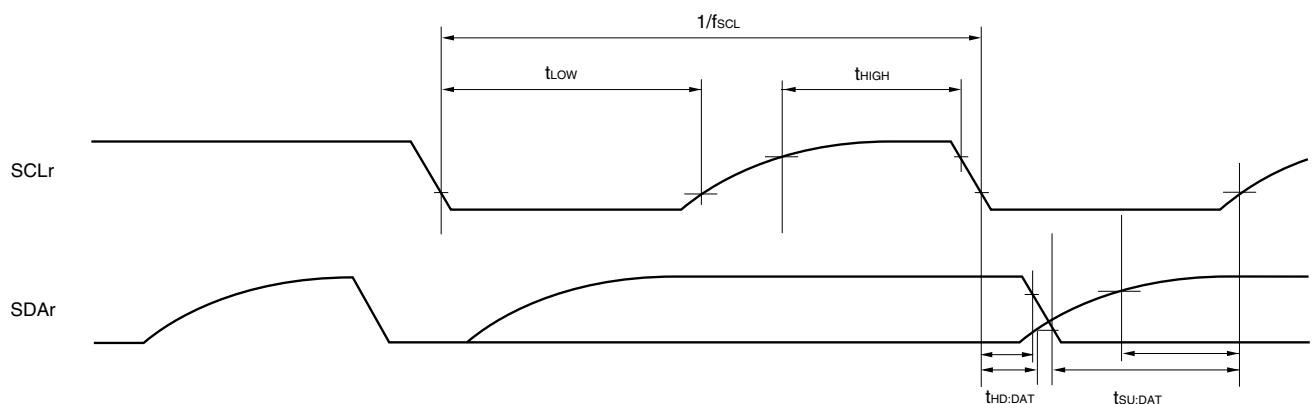
**CSI mode serial transfer timing (master mode) (during communication at different potential)**

(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remarks 1. p: CSI number (p = 00, 01, 10, 20, 30, 31), m: Unit number (m = 00, 01, 02, 10, 12, 13), n: Channel number (n = 0, 2), g: PIM and POM number (g = 0, 1, 4, 5, 8, 14)

2. CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential. Use other CSI for communication at different potential.

Simplified I²C mode connection diagram (during communication at different potential)**Simplified I²C mode serial transfer timing (during communication at different potential)**

Caution Select the TTL input buffer and the N-ch open drain output (V_{DD} tolerance (for the 20- to 52-pin products)/EV_{DD} tolerance (for the 64- to 100-pin products)) mode for the SDAr pin and the N-ch open drain output (V_{DD} tolerance (for the 20- to 52-pin products)/EV_{DD} tolerance (for the 64- to 100-pin products)) mode for the SCLr pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL} , see the DC characteristics with TTL input buffer selected.

Remarks

- 1. $R_b[\Omega]$: Communication line (SDAr, SCLr) pull-up resistance, $C_b[F]$: Communication line (SDAr, SCLr) load capacitance, $V_b[V]$: Communication line voltage
- 2. r: IIC number (r = 00, 01, 10, 20, 30, 31), g: PIM, POM number (g = 0, 1, 4, 5, 8, 14)
- 3. f_{MCK} : Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00, 01, 02, 10, 12, 13))

3.6.5 Power supply voltage rising slope characteristics

($T_A = -40$ to $+105^\circ\text{C}$, $V_{SS} = 0$ V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	S_{VDD}				54	V/ms

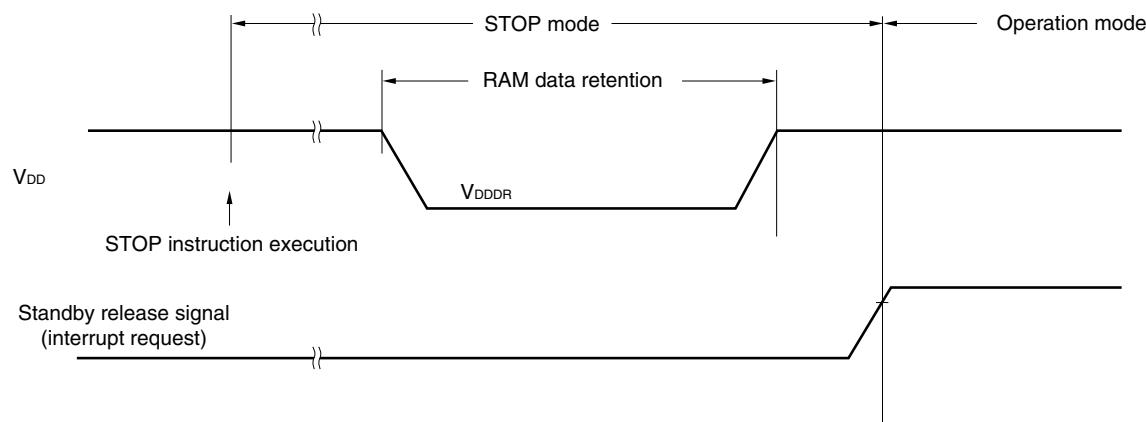
Caution Make sure to keep the internal reset state by the LVD circuit or an external reset until V_{DD} reaches the operating voltage range shown in 3.4 AC Characteristics.

3.7 RAM Data Retention Characteristics

($T_A = -40$ to $+105^\circ\text{C}$, $V_{SS} = 0$ V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention supply voltage	V_{DDDR}		1.44 ^{Note}		5.5	V

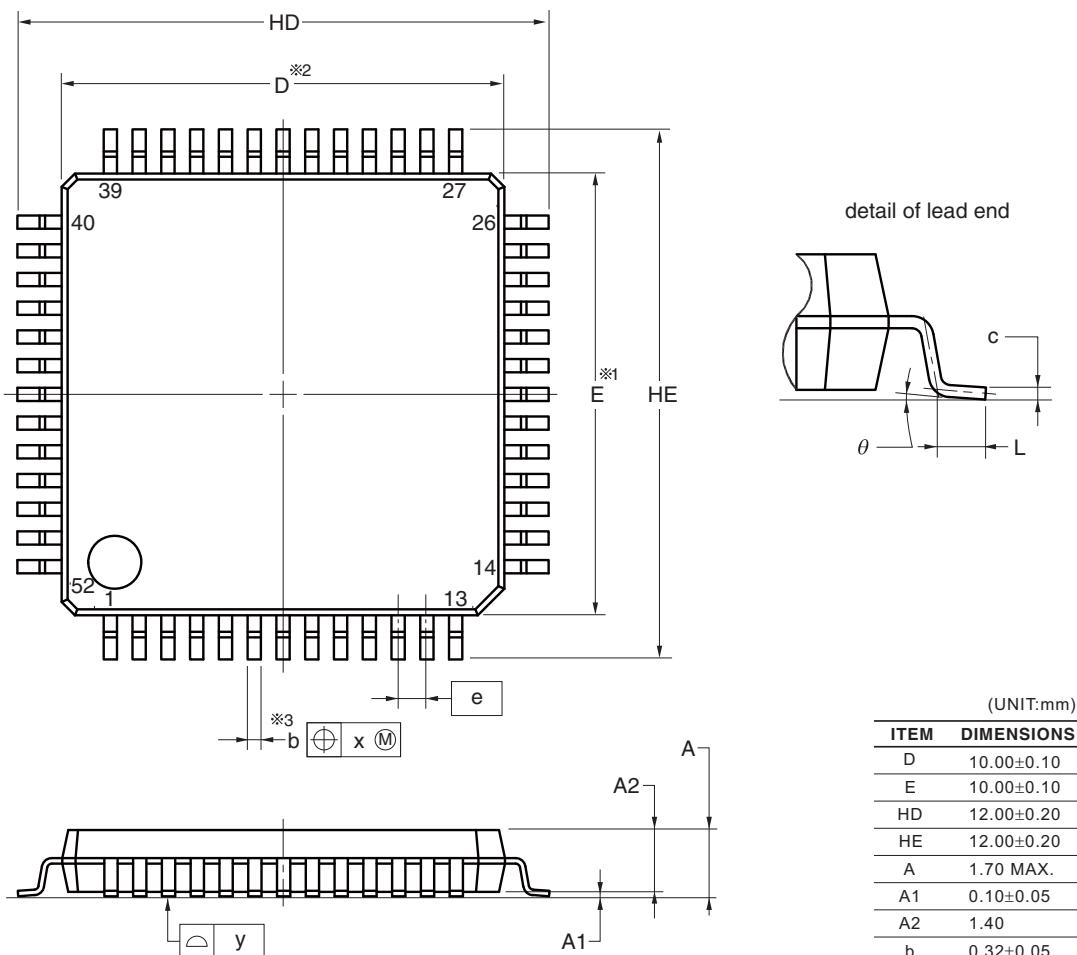
Note This depends on the POR detection voltage. For a falling voltage, data in RAM are retained until the voltage reaches the level that triggers a POR reset but not once it reaches the level at which a POR reset is generated.



4.10 52-pin Products

R5F100JCAFA, R5F100JDAFA, R5F100JEAF, R5F100JFAFA, R5F100JGAF, R5F100JHAF, R5F100JJAF,
 R5F100JKAF, R5F100JLAF
 R5F101JCAFA, R5F101JDAFA, R5F101JEAF, R5F101JFAFA, R5F101JGAF, R5F101JHAF, R5F101JJAF,
 R5F101JKAF, R5F101JLAF
 R5F100JCDFA, R5F100JDDFA, R5F100JEDFA, R5F100JFDFA, R5F100JGDFA, R5F100JHDFA, R5F100JJDF,
 R5F100JKDFA, R5F100JLDFA
 R5F101JCDFA, R5F101JDDFA, R5F101JEDFA, R5F101JFDFA, R5F101JGDFA, R5F101JHDFA, R5F101JJDF,
 R5F101JKDFA, R5F101JLDFA
 R5F100JCGFA, R5F100JDGFA, R5F100JEGFA, R5F100JFGFA, R5F100JGGFA, R5F100JHGFA, R5F100JJGFA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LQFP52-10x10-0.65	PLQP0052JA-A	P52GB-65-GBS-1	0.3



(UNIT:mm)	
ITEM	DIMENSIONS
D	10.00±0.10
E	10.00±0.10
HD	12.00±0.20
HE	12.00±0.20
A	1.70 MAX.
A1	0.10±0.05
A2	1.40
b	0.32±0.05
c	0.145±0.055
L	0.50±0.15
θ	0° to 8°
e	0.65
x	0.13
y	0.10

NOTE

1. Dimensions “*1” and “*2” do not include mold flash.
2. Dimension “*3” does not include trim offset.

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